

## Description

The 74AHCT1G126Q is an automotive compliant, single non-inverting buffer/bus driver with a 3-state output. The output enters a high impedance state when a LOW-level is applied to the output enable (OE) pin. The device is designed for operation with a power supply range of 4.5V to 5.5V.

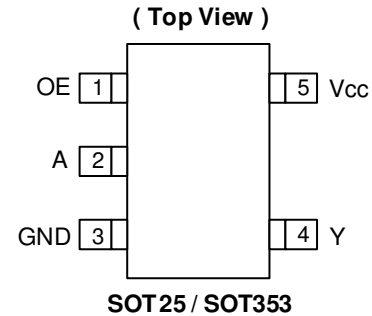
## Features

- Grade 1 Ambient Temperature Operation: -40°C to +125°C
- Supply Voltage Range from 4.5V to 5.5V
- ±8mA Output Drive at 5.0V
- CMOS Low-Power Consumption
- Schmitt Trigger Action at All Inputs Make the Circuit Tolerant for Slower Input Rise and Fall Time
- Inputs Not Limited by Vcc
- Balanced Propagation Delays
- Balanced Drive Capability
- ESD Protection Tested per AEC-Q100
- Exceeds 2000-V Human Body Model (AEC-Q100-002)
- Exceeds 1000-V Charged Device Model (AEC-Q100-011)
- Latch-Up Exceeds 100mA (AEC-Q100-004)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The 74AHCT1G126Q is suitable for automotive applications requiring specific change control; this part is AEC-Q100 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Pin Assignments



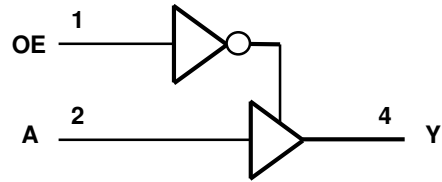
## Applications

- General Purpose Logic
- Wide Array of Products, such as:
  - Automotive Applications within Grade 1 Temperature Range
  - Industrial Computing/Controls/Automation
  - High Reliability Networking/Communications
  - Industrial/Agricultural Equipment

### Pin Descriptions

Pin Name	Description
OE	Output Enable Active HIGH
A	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

### Logic Diagram



### Function Table

Inputs		Output
OE	A	Y
H	H	H
H	L	L
L	X	Z

### Absolute Maximum Ratings (Notes 4 & 5)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
V <sub>I</sub>	Input Voltage Range	-0.5 to 6.5	V
V <sub>O</sub>	Voltage Applied to Output in High or Low State	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output Clamp Current (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20	mA
I <sub>O</sub>	Continuous Output Current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±25	mA
I <sub>CC</sub>	Continuous Current Through V <sub>CC</sub>	75	mA
I <sub>GND</sub>	Continuous Current Through GND	-75	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>D</sub>	Total Power Dissipation (Note 6)	250	mW

- Notes:
- Stresses beyond the absolute maximum can result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
  - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.
  - This will need to be derated at higher operating temperatures to prevent exceeding maximum T<sub>J</sub>. Refer to package thermal characteristics section.

### Recommended Operating Conditions (Note 7)

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	Operating Voltage	—	4.5	5.5	V
V <sub>IH</sub>	High-Level Input Voltage	V <sub>CC</sub> = 5V ± 0.5V	2.0	—	V
V <sub>IL</sub>	Low-Level Input Voltage	V <sub>CC</sub> = 5V ± 0.5V	—	0.8	V
V <sub>I</sub>	Input Voltage		0	5.5	V
V <sub>O</sub>	Output Voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-Level Output Current	V <sub>CC</sub> = 5V ± 0.5V	—	-8	mA
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 5V ± 0.5V	—	8	mA
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 5V ± 0.5V	—	20	ns/V
T <sub>A</sub>	Ambient Temperature	—	-40	+125	°C

Note: 7. Unused inputs should be held at V<sub>CC</sub> or Ground.

### Electrical Characteristics (All typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C.)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	+25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	High Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -50μA	4.5V	4.4	4.5	—	4.4	—	4.4	—	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -8mA	4.5V	3.94	—	—	3.8	—	3.70	—	V
V <sub>OL</sub>	Low Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50μA	4.5V	—	0	0.1	—	0.1	—	0.1	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 8mA	4.5V	—	—	0.36	—	0.44	—	0.55	V
I <sub>OZ</sub>	Z State Leakage Current	V <sub>I</sub> = 5.5V or GND V <sub>O</sub> = 0 to 5.5V	5.5V	—	—	0.25	—	2.5	—	10	μA
I <sub>I</sub>	Input Current	V <sub>I</sub> = 5.5V or GND	0 to 5.5V	—	—	±0.1	—	±1	—	±2	μA
ΔI <sub>CC</sub>	Additional Supply Current	Per input pin; V <sub>I</sub> = 3.4V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5V	—	—	1.35	—	1.5	—	1.5	mA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = 5.5V or GND I <sub>O</sub> = 0	5.5V	—	—	1	—	10	—	40	μA
C <sub>I</sub>	Input Capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5V	—	1.5	10	—	10	—	10	pF

### Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Typ	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT25	Note 8	—	184	—	°C/W
		SOT353		—	385	—	
$\theta_{JC}$	Thermal Resistance Junction-to-Case	SOT25	Note 8	—	62	—	°C/W
		SOT353		—	164	—	

Note: 8. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

### Switching Characteristics

V<sub>CC</sub> = 5V ± 0.5V (See Figure 1, Typical values at V<sub>CC</sub> = 5V.)

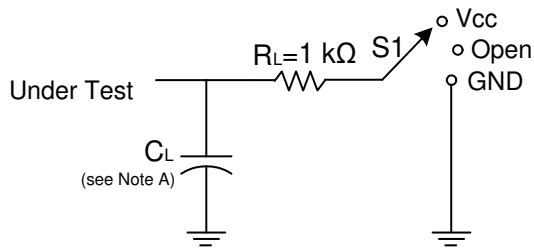
Parameter	From (Input)	To (Output)	Test Conditions	+25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t <sub>PD</sub>	A	Y	C <sub>L</sub> = 15pF	1.0	3.4	5.5	1.0	6.5	1.0	7.0	ns
			C <sub>L</sub> = 50pF	1.0	4.8	7.5	1.0	8.5	1.0	9.5	ns
t <sub>EN</sub>	OE	Y	C <sub>L</sub> = 15pF	1.0	3.9	5.1	1.0	6.0	1.0	6.5	ns
			C <sub>L</sub> = 50pF	1.0	5.1	7.5	1.0	9.0	1.0	9.5	ns
t <sub>DIS</sub>	OE	Y	C <sub>L</sub> = 15pF	1.0	4.5	6.8	1.0	8.0	1.0	8.5	ns
			C <sub>L</sub> = 50pF	1.0	6.1	8.8	1.0	10.0	1.0	11.0	ns

### Operating Characteristics

T<sub>A</sub> = +25°C

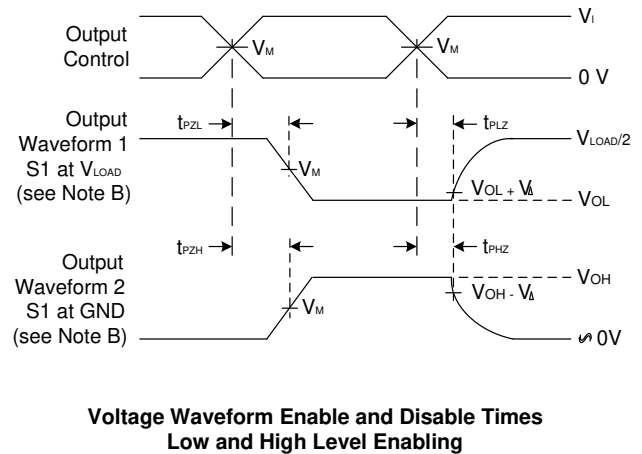
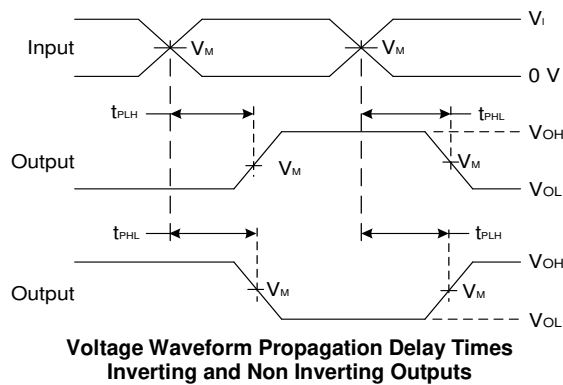
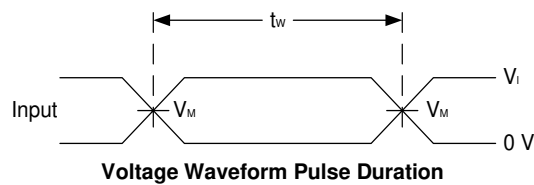
Parameter	Test Conditions	Typ	Unit
C <sub>PD</sub>	V <sub>CC</sub> = 5.0V, f = 1MHz C <sub>L</sub> = 50pF V <sub>I</sub> = GND to V <sub>CC</sub>	11	pF

**Measurement Information**



Test	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

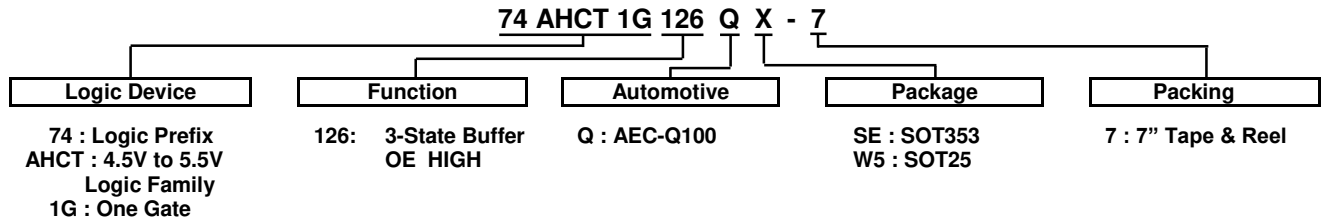
$V_{CC}$	Inputs		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_i$	$t_R/t_F$					
$5V \pm 0.5V$	GND to 3V	$\leq 2.5ns$	1.5V	$V_{CC}$	15pF	1kΩ	0.3V
$5V \pm 0.5V$	GND to 3V	$\leq 2.5ns$	1.5V	$V_{CC}$	50pF	1kΩ	0.3V



**Figure 1. Load Circuit and Voltage Waveforms**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq 1MHz$ .
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{DIS}$ .
  - E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN}$ .
  - F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

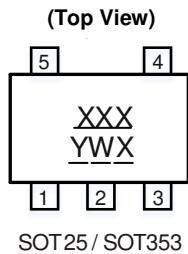
## Ordering Information (Note 9)



Part Number	Package Code	Package (Notes 10 & 11)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74AHCT1G126QSE-7	SE	SOT353	2.15mm × 2.1mm × 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74AHCT1G126QW5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm lead pitch	3000/Tape & Reel	-7

Notes: 9. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.  
 10. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
 11. The taping orientation is located on our website at <https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf>.

## Marking Information



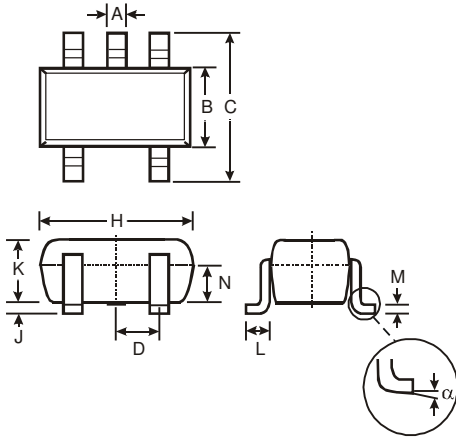
**XXX** : Identification Code  
**Y** : Year 0~9  
**W** : Week: A~Z 1~26 week  
       a~z 27~52 week  
       z represents week 52 and 53  
**X** : A~Z : Internal Code

Part Number	Package	Identification Code
74AHCT1G126QW5-7	SOT25	ZZQ
74AHCT1G126QSE-7	SOT353	ZZQ

**Package Outline Dimensions**

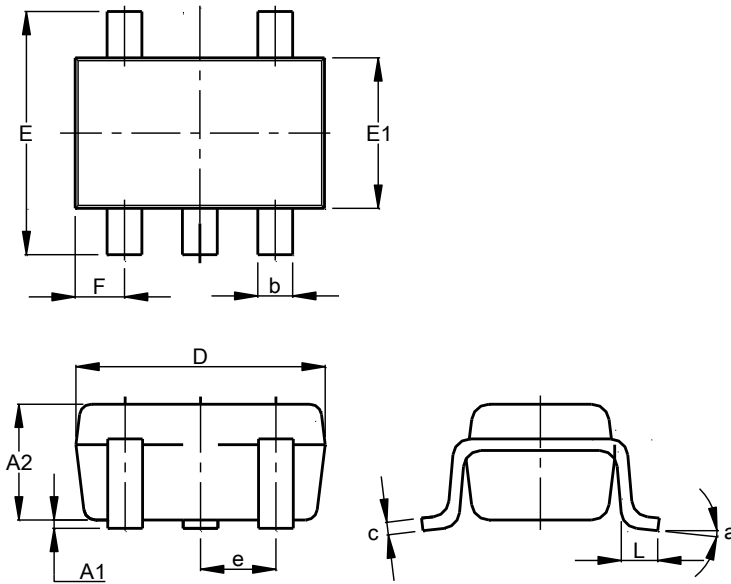
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

(2) Package Type: SOT353

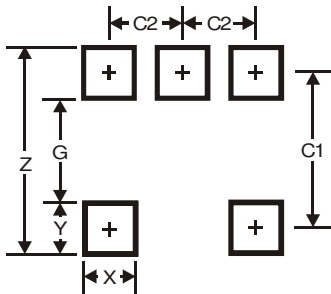


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

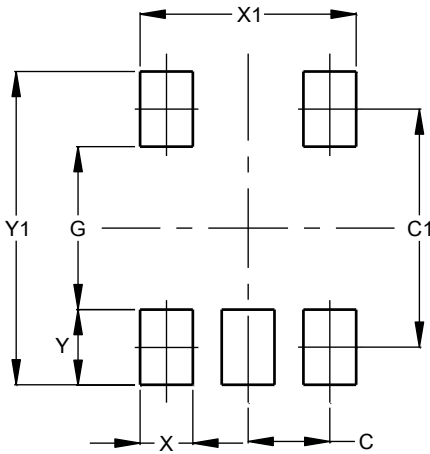
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### (1) Package Type: SOT25



Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

### (2) Package Type: SOT353



Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

## Mechanical Data

### SOT25

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0158 grams (Approximate)

### SOT353

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0064 grams (Approximate)



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